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ISSUE DATE

U.S. UTILITY Patent Application

10/069517

APPL NUM 10069517	FILING DATE 03/05/2002	CLASS 438	SUBCLASS 748	GAU 2812	EXAMINER GUERREIRO
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OK MC
**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A 371 OF PCT/FR00/02468 09/07/2000

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**FOREIGN APPLICATIONS VERIFIED:
FRANCE 99 11224 09/08/1999

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 220040US2PCT
35 USC 119 conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials	MC	
TITLE : Method for electrically conductive bonding between two semiconductor elements		
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE		Total Claims	Print Claim for O.G.
Amount Due	Date Paid	DRAWING	
<input type="checkbox"/> TERMINAL DISCLAIMER		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> PREPARED FOR ISSUE		Application Examiner	
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